

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of
Daisuke OKAMURA et al.
Serial No. (unknown)
Filed herewith



METHOD OF RECYCLING MOLD PLASTIC
PARTS FOR PHOTSENSITIVE MATERIAL
AND A RECYCLED PLASTIC MOLD PARTS

INFORMATION DISCLOSURE STATEMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying document, a copy of which is attached to this statement, is made of record on the enclosed sheet.

A concise explanation of the relevance of this item is that we are advised by our client that this reference was discovered during any searches they or their client had made, or that it was considered in the preparation of the application.

Respectfully submitted,

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By

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September 27, 2001

FORM PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK		ATTY. DOCKET NO. KP-9010	SERIAL NO.
OFFICE		APPLICANT Daisuke OKAMURA et al.	
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)		FILING DATE September 27, 2001	GROUP
(37 CFR 1.98(b))			



U.S. PATENT DOCUMENTS

EXAMINER INITIAL		PATENT NUMBER	ISSUE DATE	PATENTEE	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						

FOREIGN PATENT OR PUBLISHED FOREIGN PATENT APPLICATION

		DOCUMENT NO.	PUBL. DATE	COUNTRY OR PATENT OF- FICE	CLASS	SUB CLASS	TRANSLATION YES NO
	AJ	JP 11-015112	01/99	Japan (with English Abstract)			no
	AK						
	AL						
	AM						
	AN						

OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

	AO	
	AP	

EXAMINER	DATE CONSIDERED
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EXAMINER: Initial citation considered. Draw line through citation if not in conformance and not considered.
Include copy of this form with next communication to applicant.